

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2194iukg#pbf

(Engineering Calculation)

QFN 7mm X 8mm Exp. Pad

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TOTAL MASS (g) : 0.162158

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.005918 | 1000000 | 36495.1992188 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.076937 | 975000 | 474456.03125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001894 | 24000 | 11679.9423828 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000024 | 300 | 148.003509521 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000055 | 700 | 339.174713135 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.078910 | 1000000 | 486623.1875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.003848 | 1000000 | 23731.9628906 | | |
| | | External Plating Total: | | | | 0.003848 | 1000000 | 23731.9628906 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001694 | 1000000 | 10446.5800781 | | |
| Internal Plating Total: | | | | 0.001694 | 1000000 | 10446.5800781 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001972 | 750000 | 12160.9550781 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000657 | 250000 | 4051.59594727 | | |
| Die Attach Total: | | | | 0.002629 | 1000000 | 16212.5507812 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.008945 | 130000 | 55162.140625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.059177 | 860000 | 364933.46875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000688 | 10000 | 4242.76708984 | | |
| | | Encapsulation Total: | | | | 0.068810 | 1000000 | 424338.375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000349 | 1000000 | 2152.2175293 | | |
| | | | | | TOTAL MASS (g) : | 0.162158 | | |